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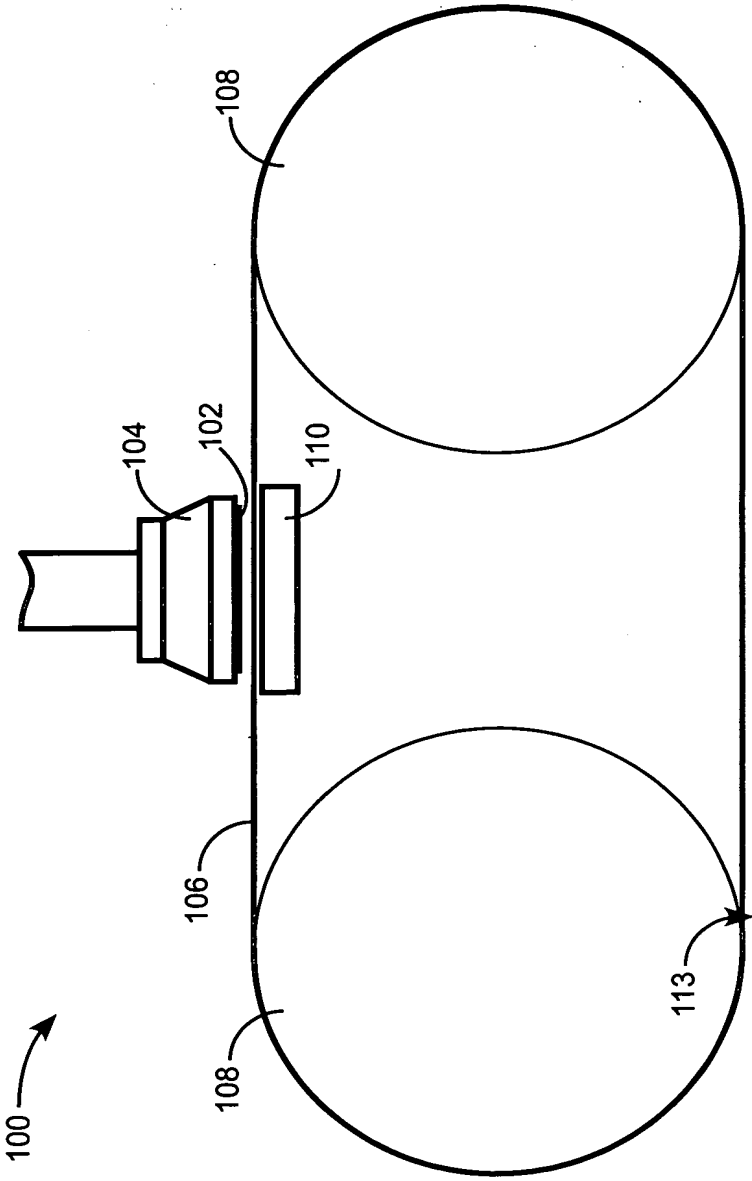


FIG. 1A

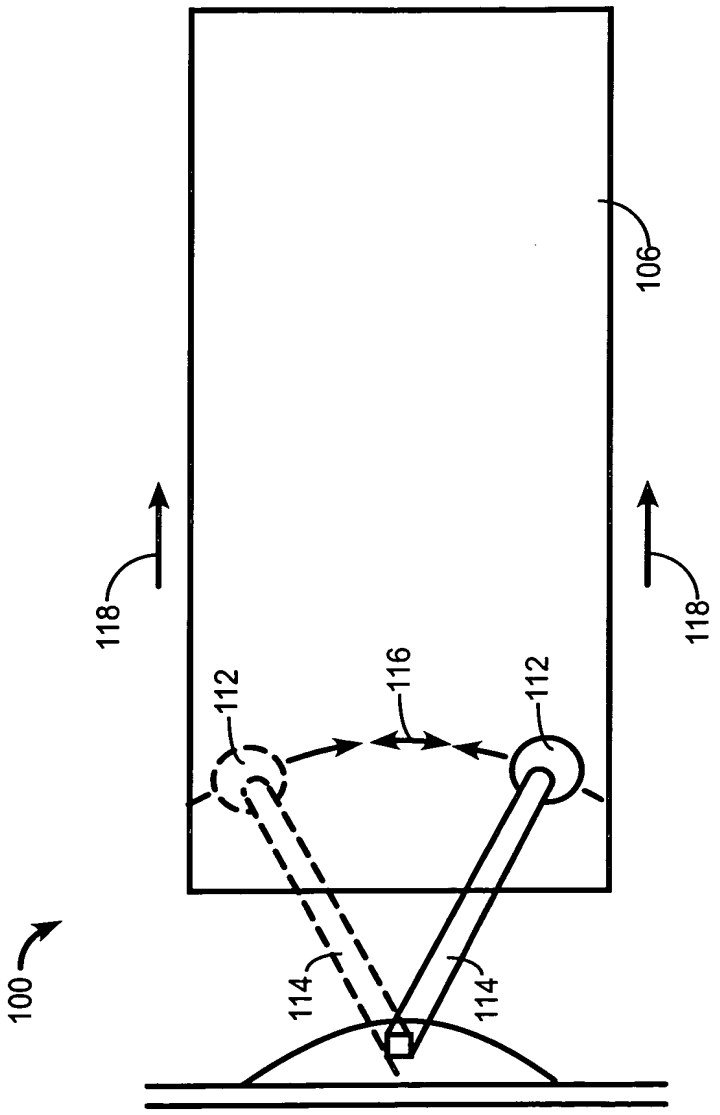


FIG. 1B

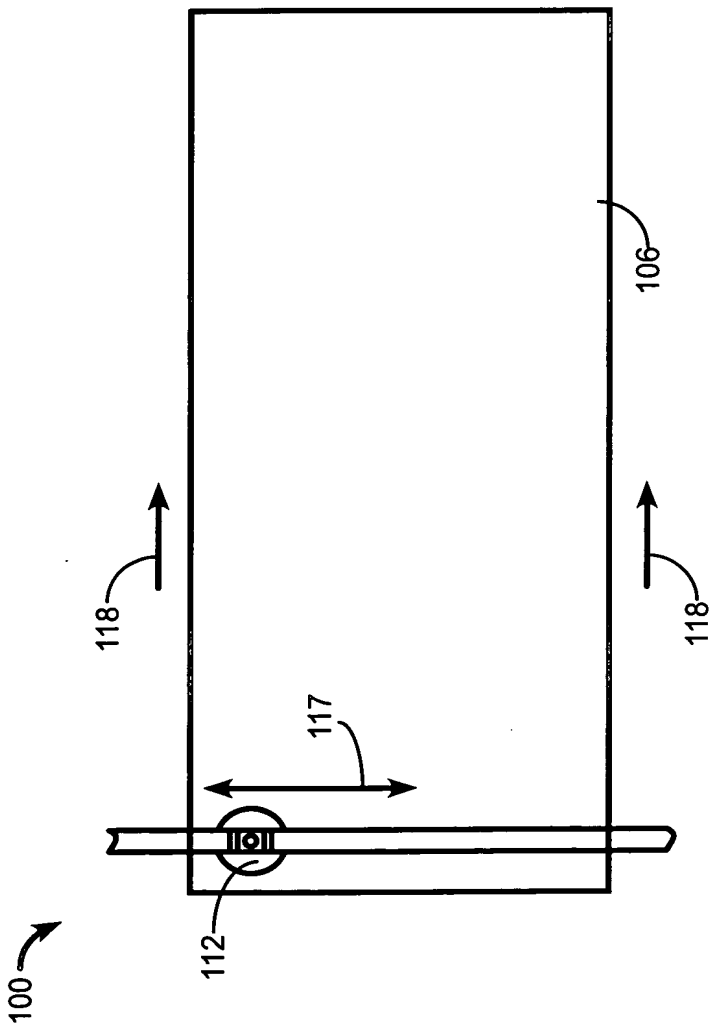


FIG. 1C

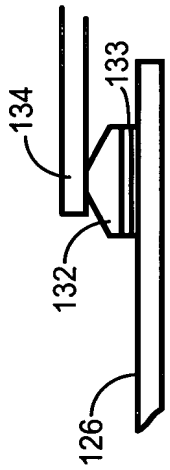


FIG. 2B

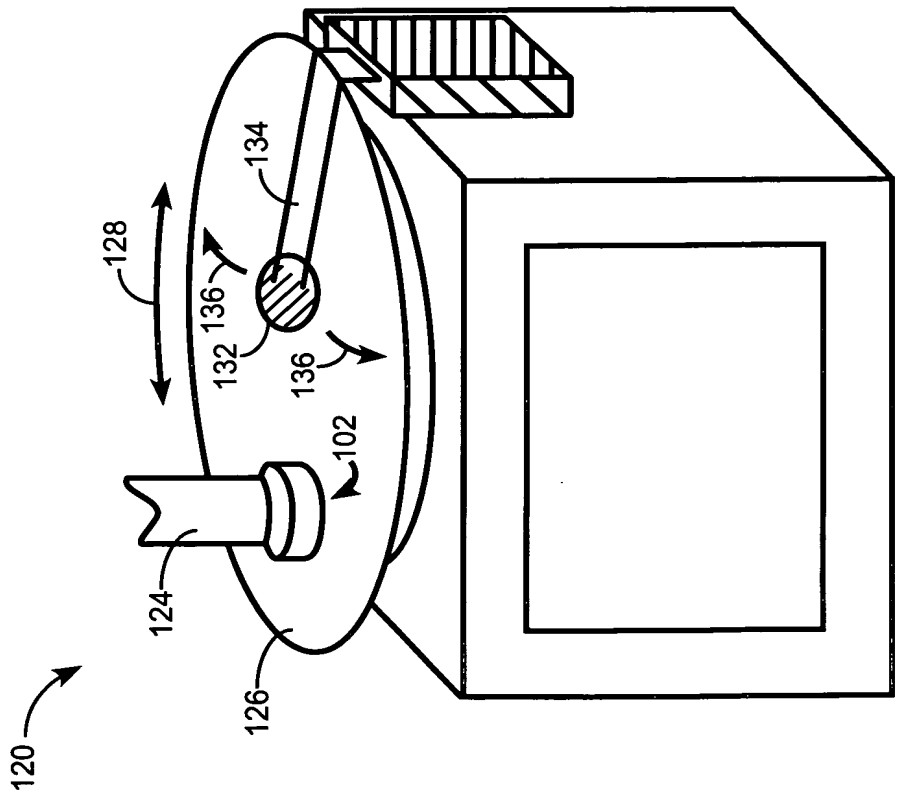


FIG. 2A

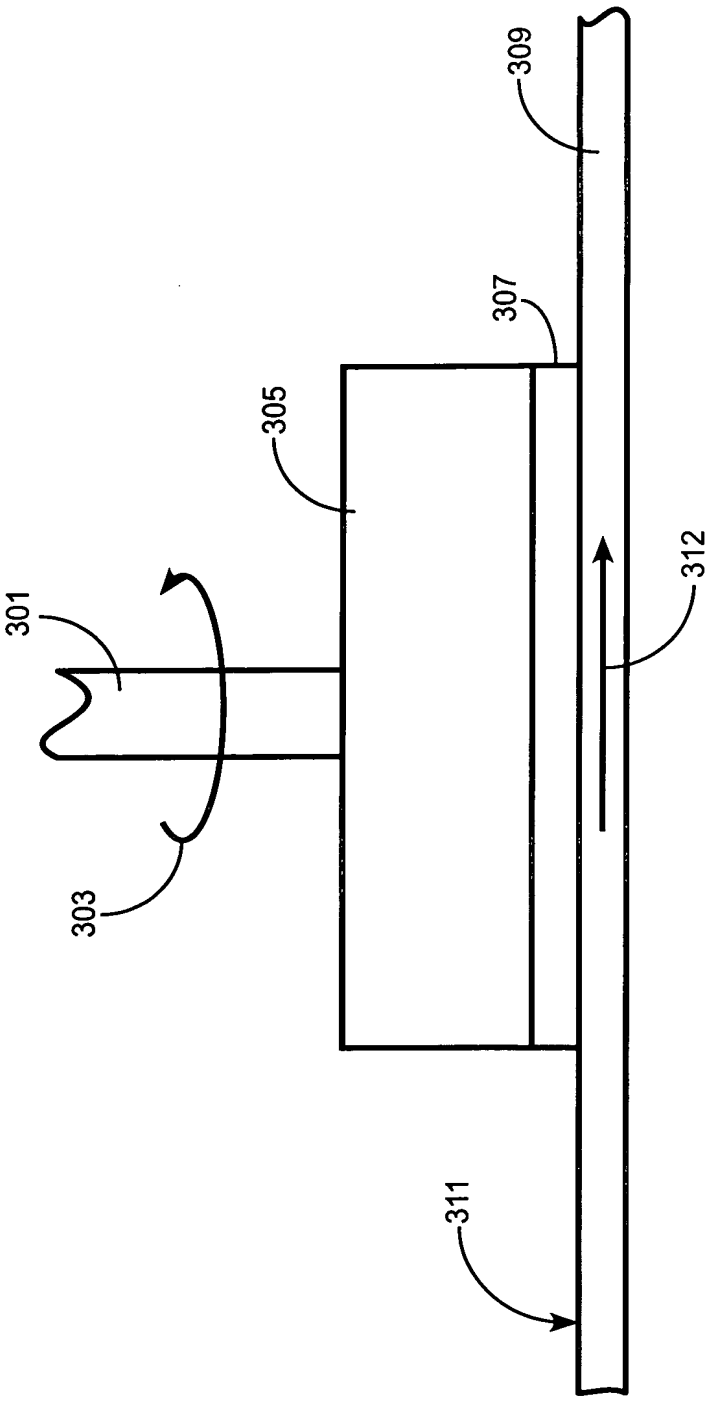


FIG. 3

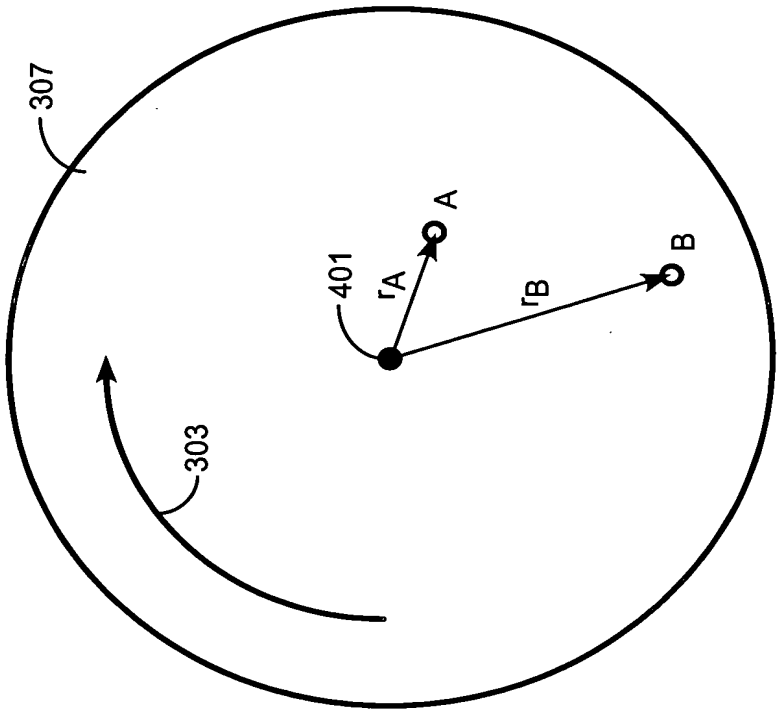


FIG. 4

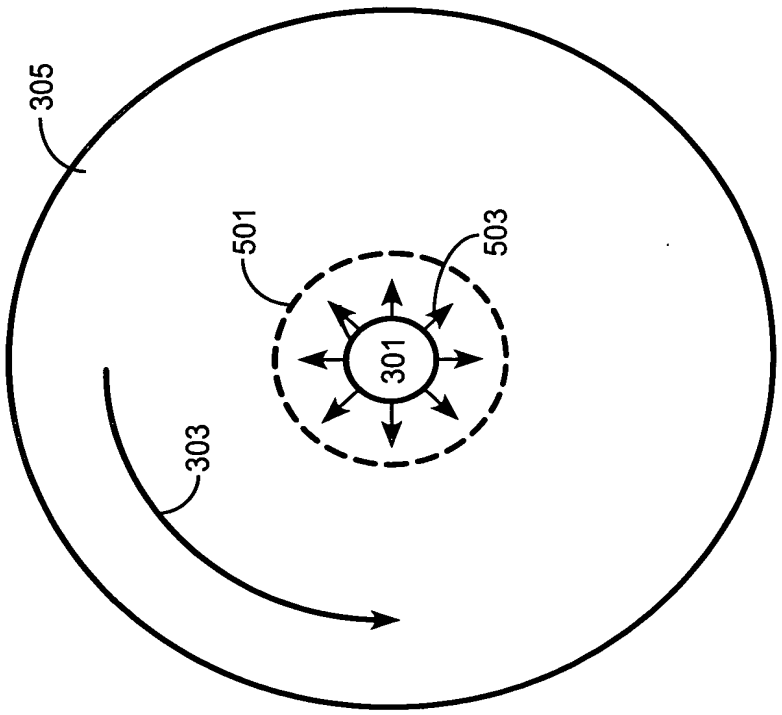


FIG. 5A

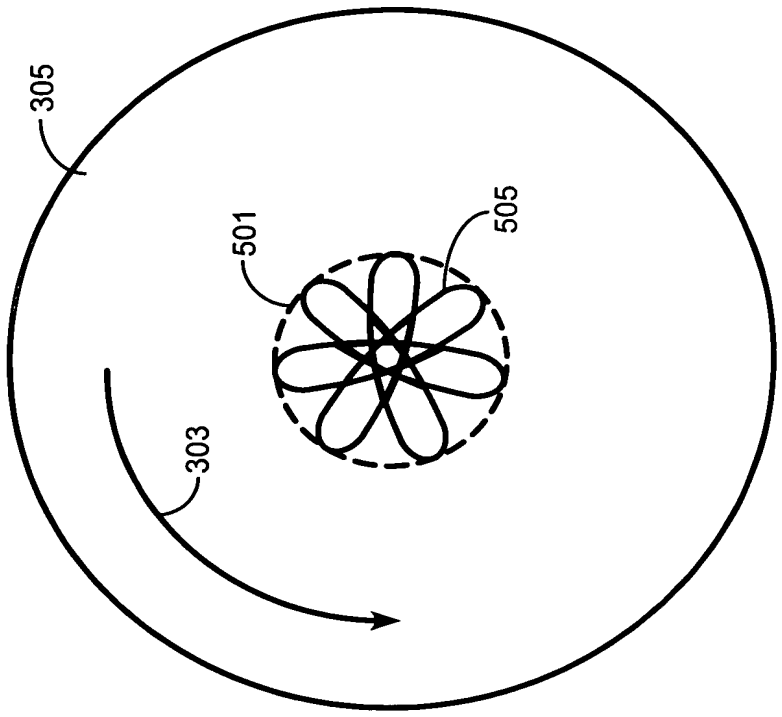


FIG. 5B

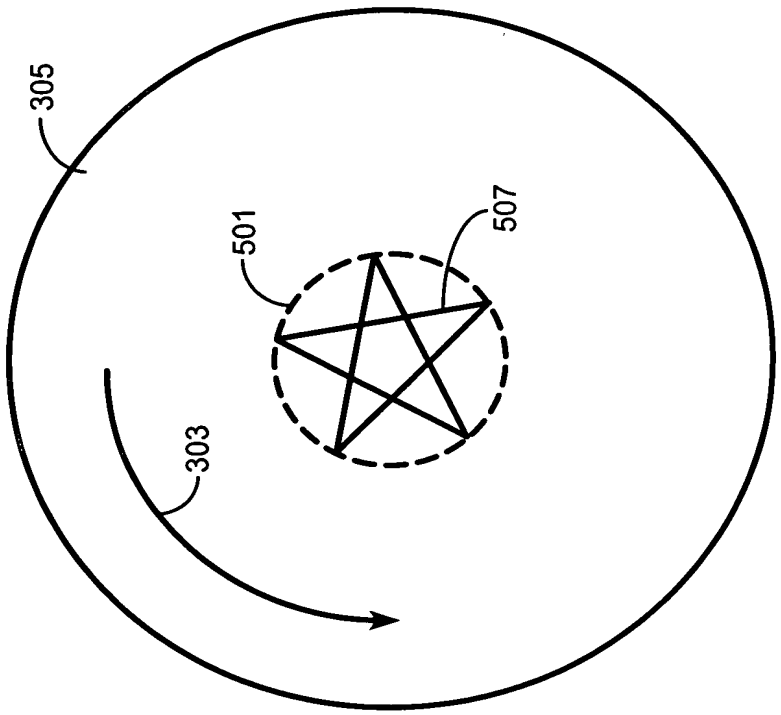


FIG. 5C

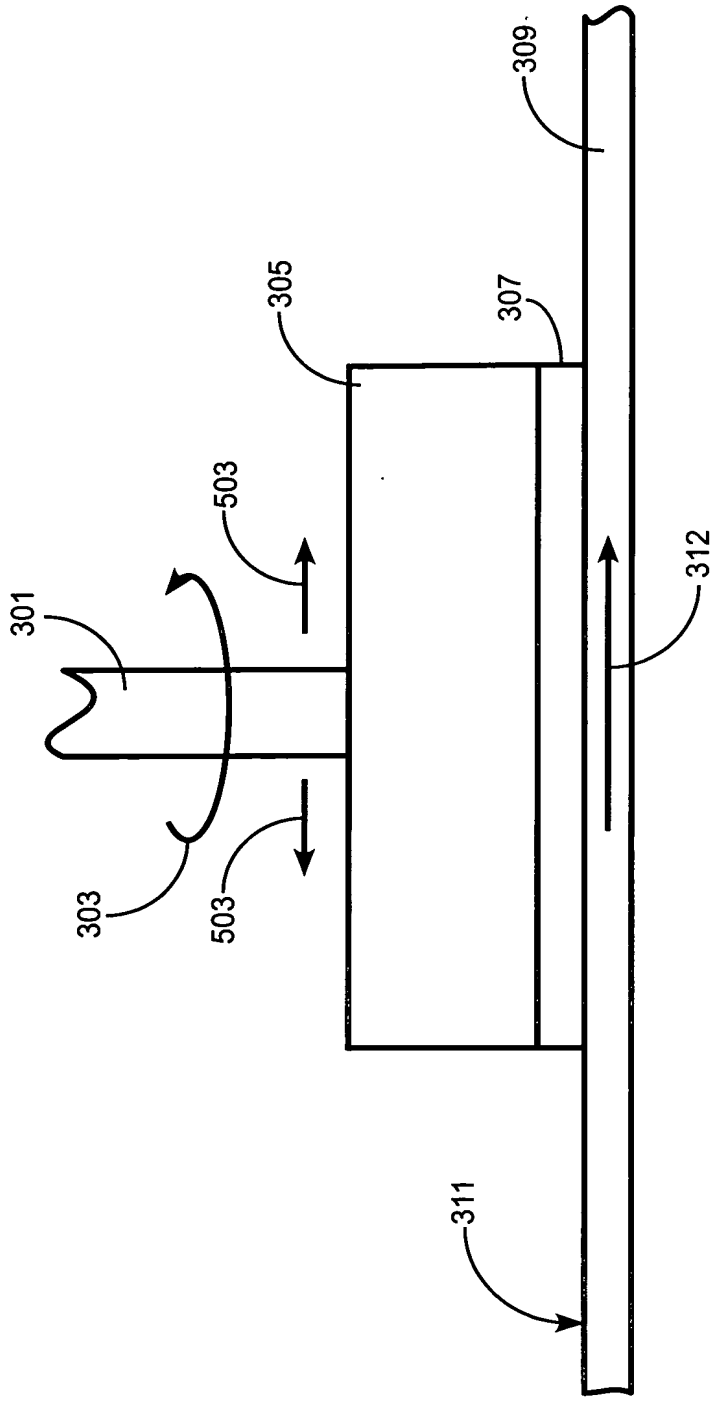


FIG. 6

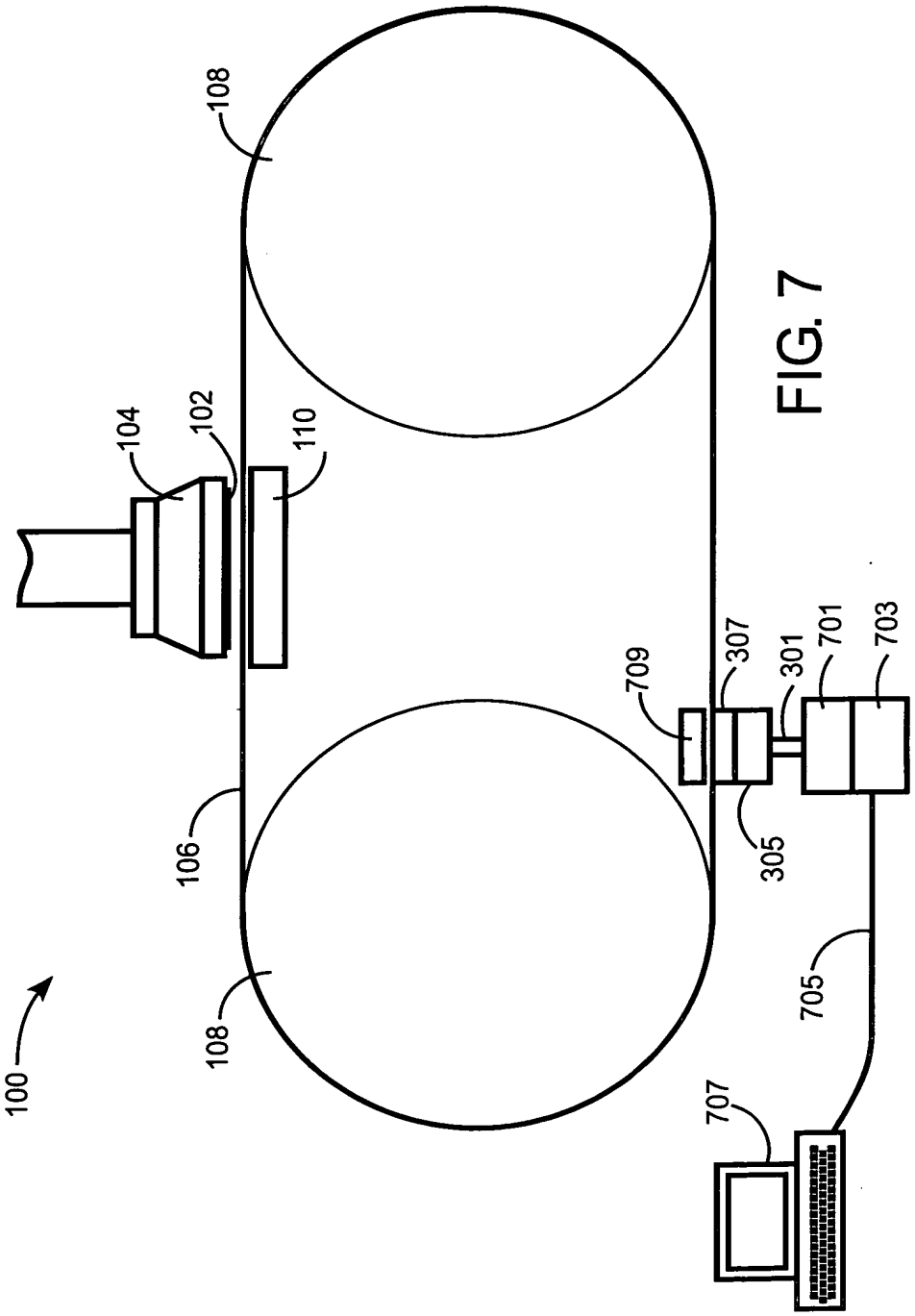


FIG. 7

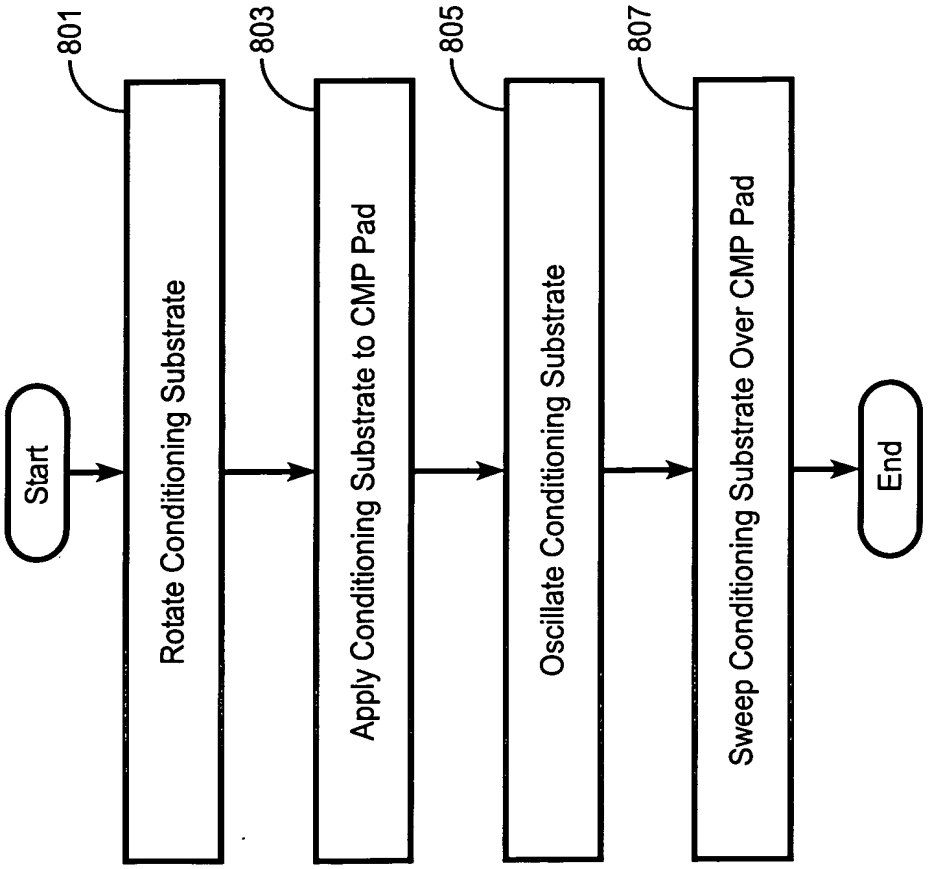

Start
801
Rotate Conditioning Substrate
803
Apply Conditioning Substrate to CMP Pad
805
Oscillate Conditioning Substrate
807
Sweep Conditioning Substrate Over CMP Pad
End

FIG. 8

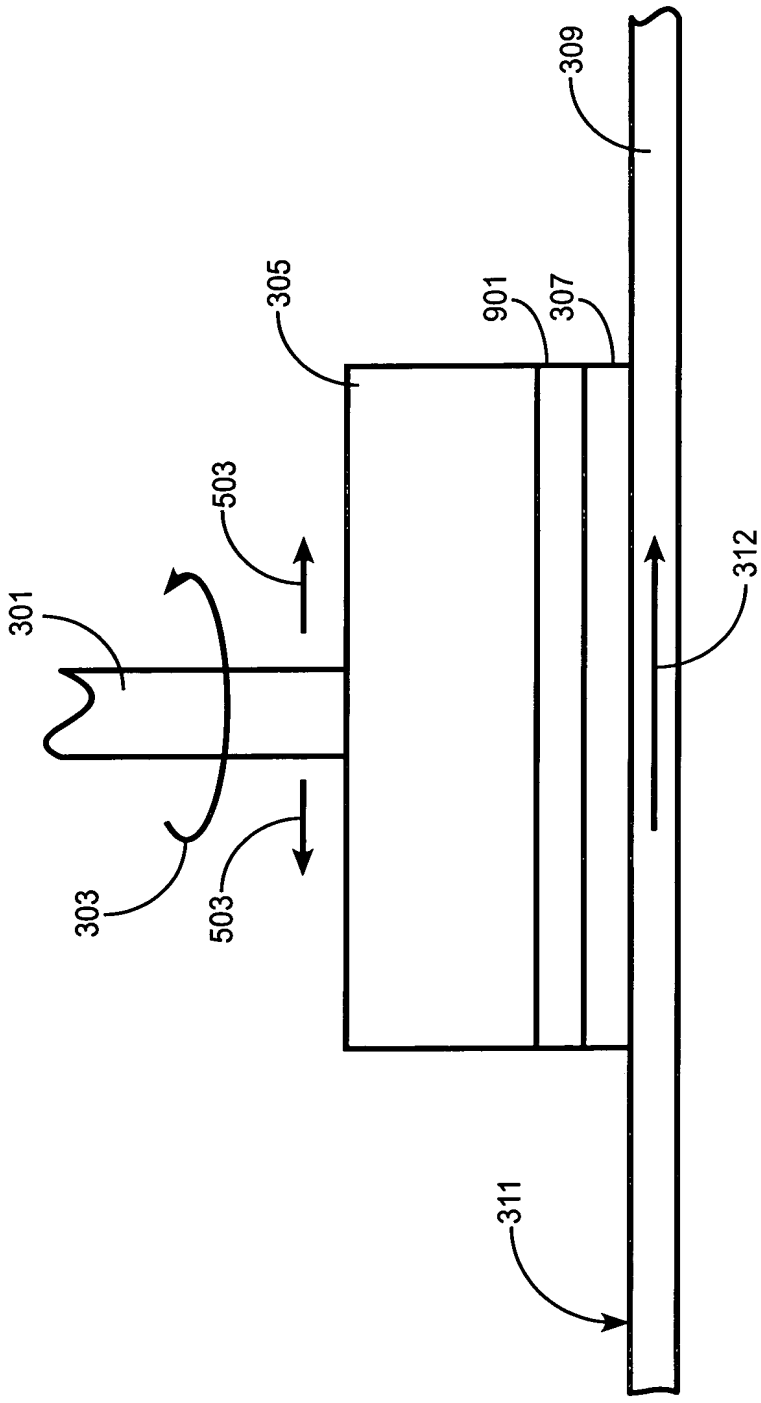


FIG. 9

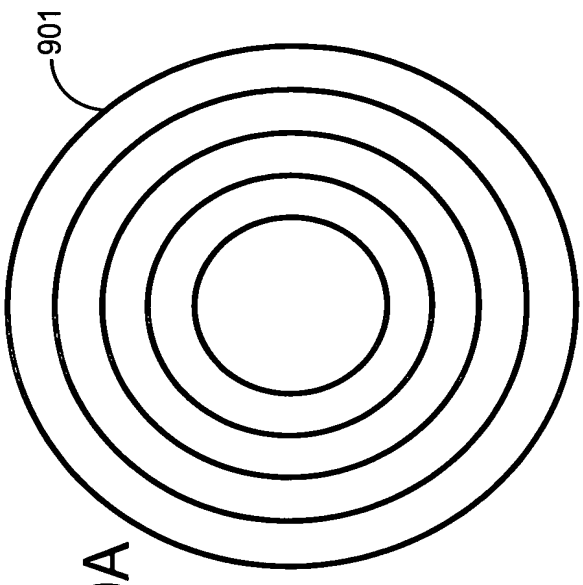


FIG. 10A

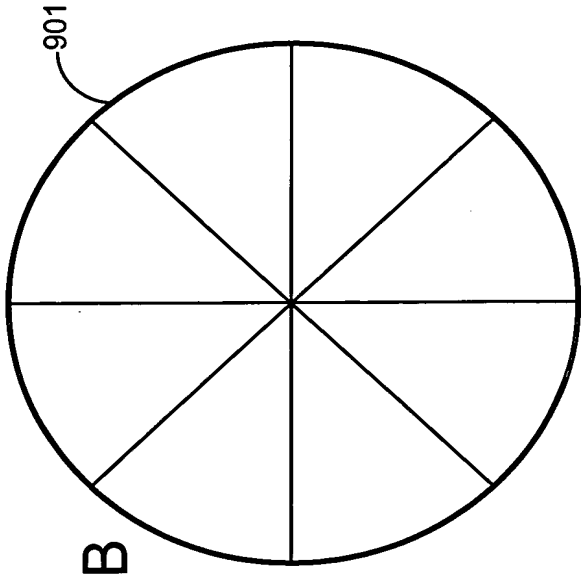


FIG. 10B

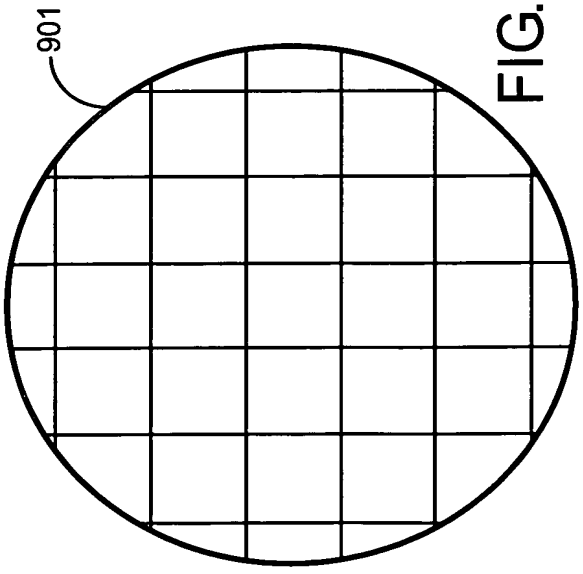


FIG. 10C

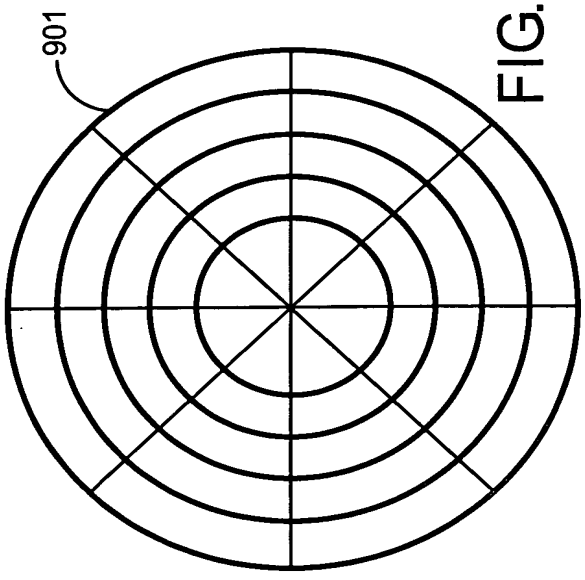


FIG. 10D

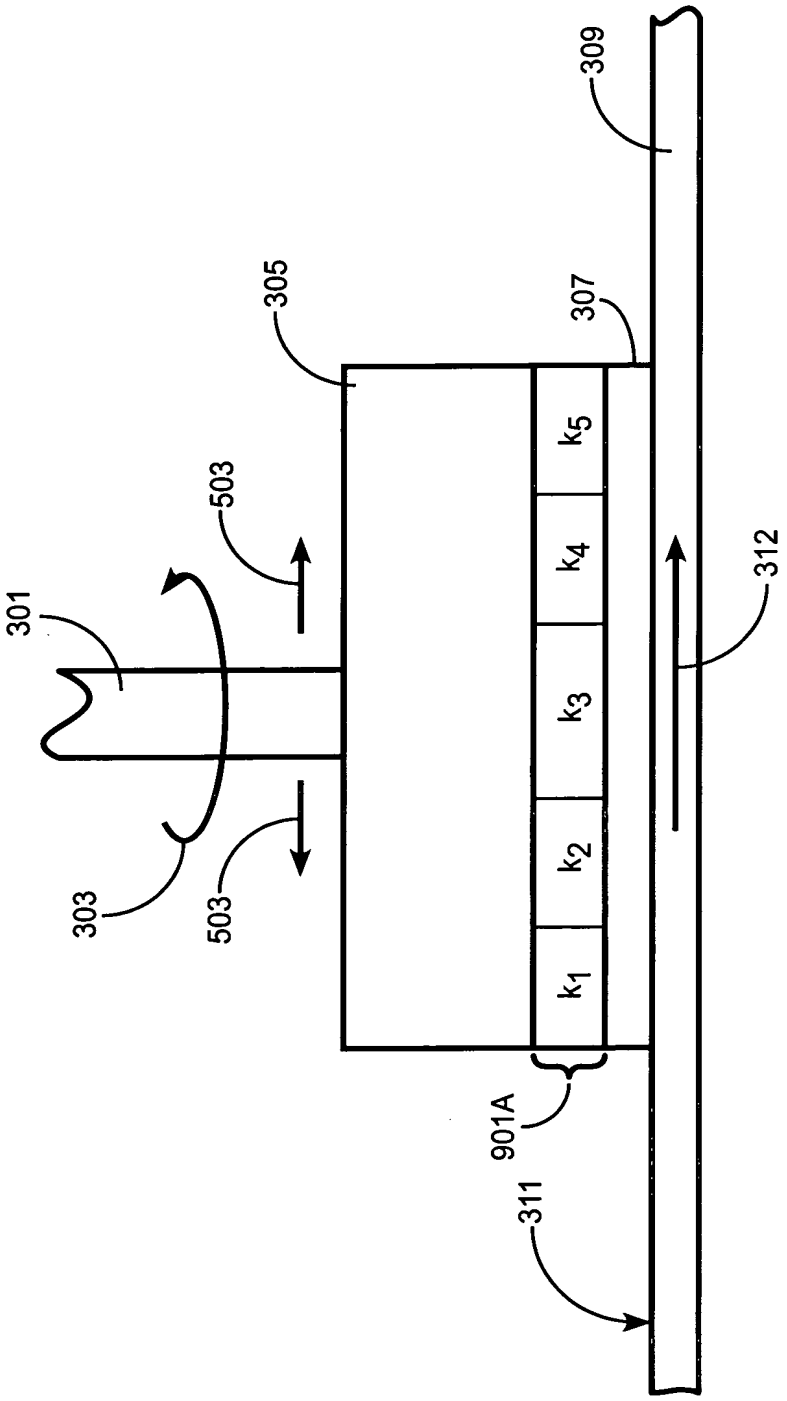


FIG. 11

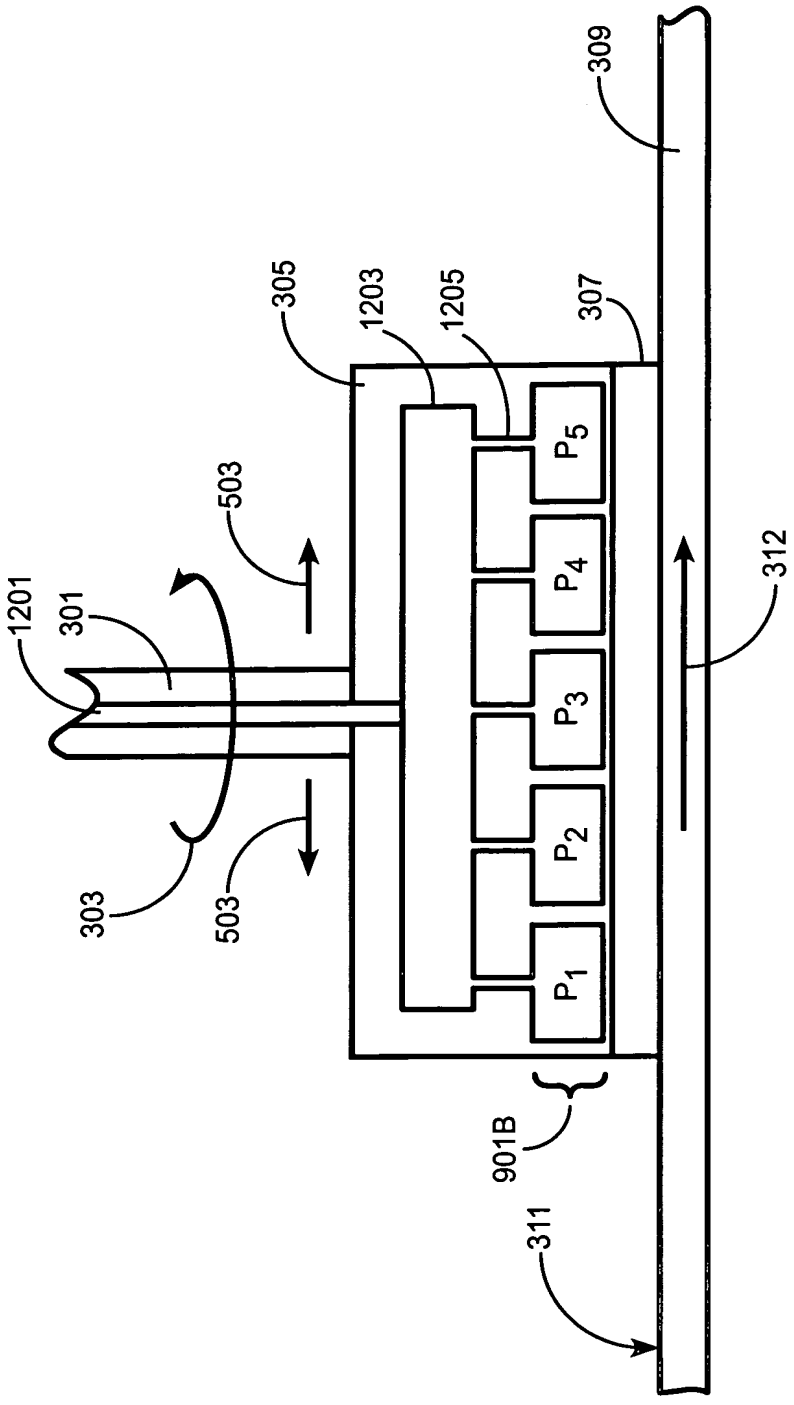

309
305
1203
1205
307
503
1201
301
312
303
503
P_5
P_4
P_3
P_2
P_1
901B
311

FIG. 12

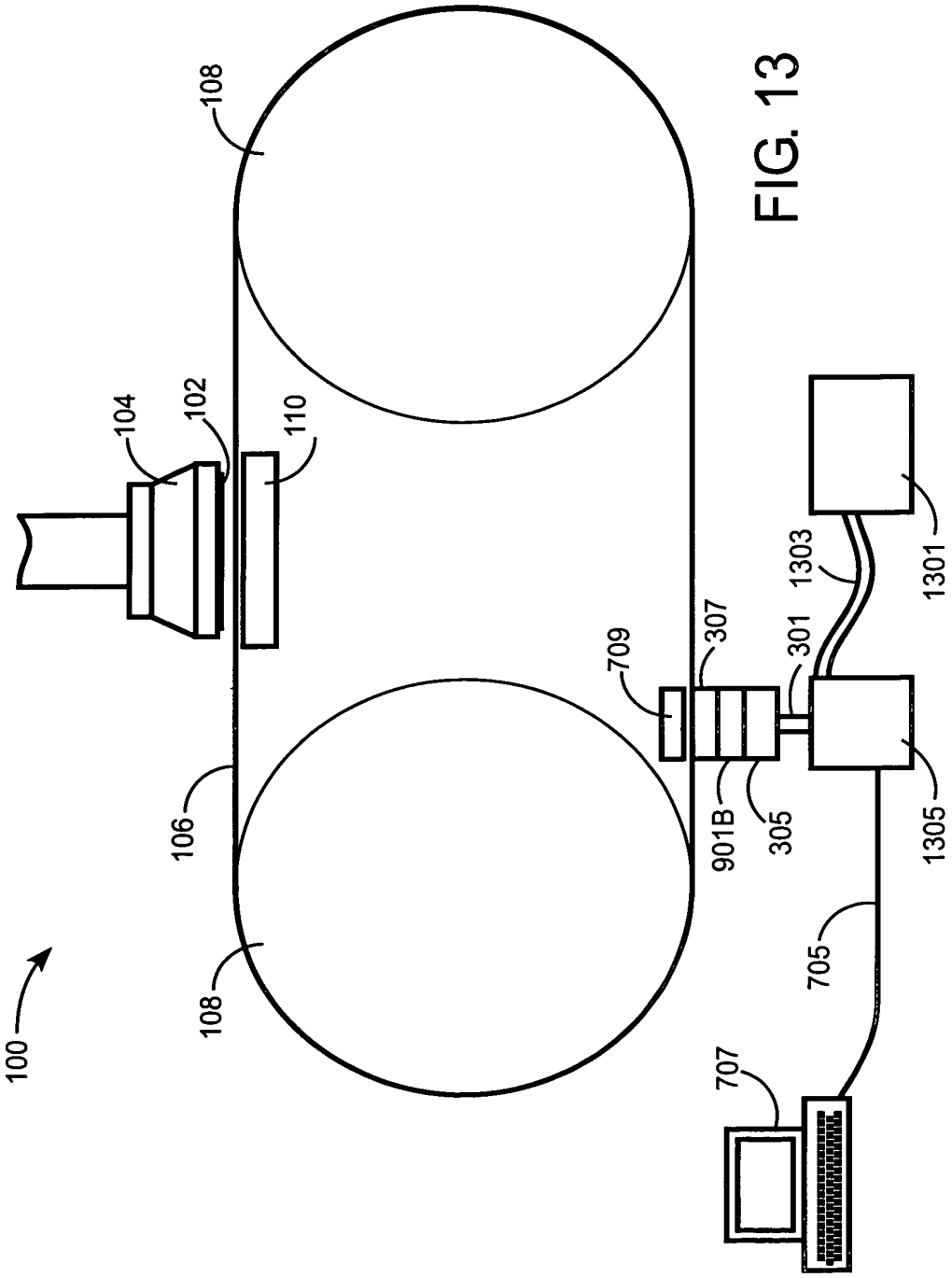
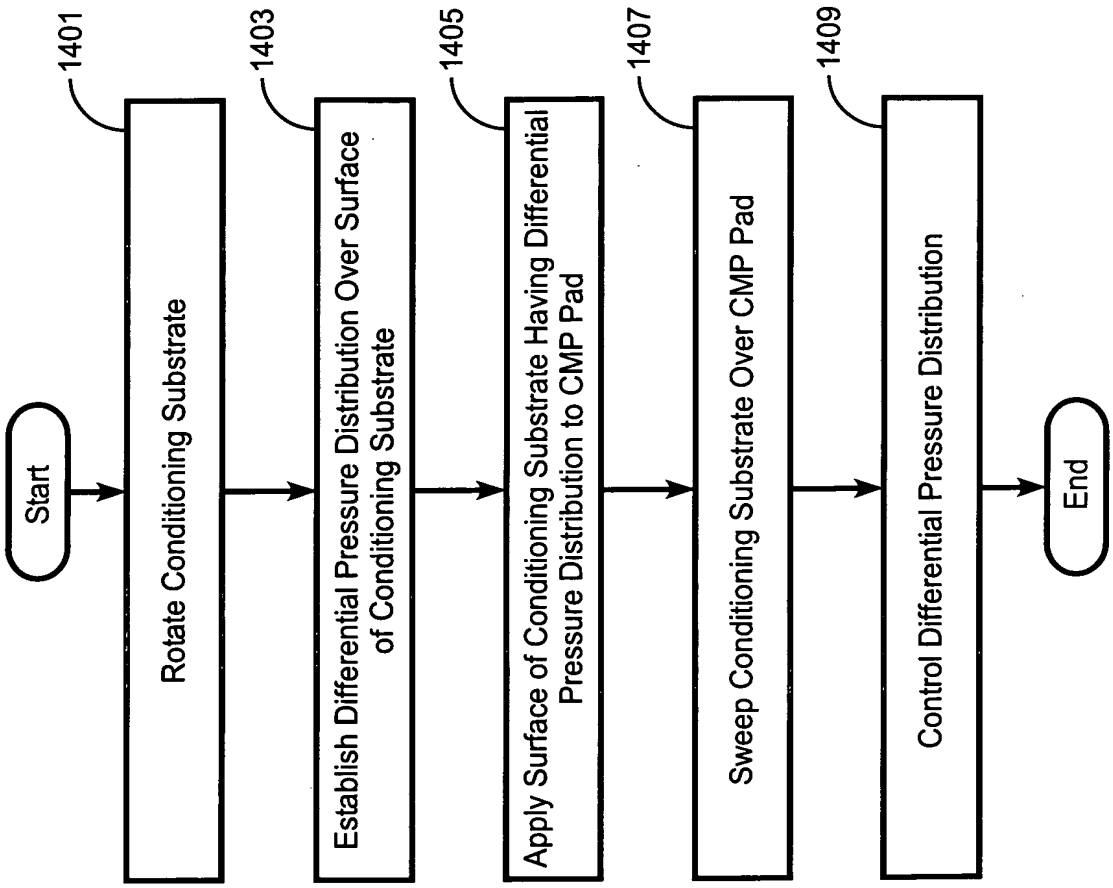

108
104
102
110
106
108
100
709
307
301
1303
1301
901B
305
1305
705
707

FIG. 13

FIG. 14


Start
1401
Rotate Conditioning Substrate
1403
Establish Differential Pressure Distribution Over Surface of Conditioning Substrate
1405
Apply Surface of Conditioning Substrate Having Differential Pressure Distribution to CMP Pad
1407
Sweep Conditioning Substrate Over CMP Pad
1409
Control Differential Pressure Distribution
End